



PK205 (v1.2) November 22,  
2012

## 100% Material Declaration Data Sheet PC20

**Average Weight: 0.6810g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Silicon Die</b>					<b>0.005380</b>	<b>0.790</b>
	Silicon	7440-21-3	100.00	Silicon IC	0.005380	
<b>Die attach material</b>					<b>0.001927</b>	<b>0.283</b>
	Epoxy Resin	Trade Secret	25.00	Glue	0.000482	
	Silver	7440-22-4	75.00	Glue	0.001445	
<b>Mold Compound</b>					<b>0.475841</b>	<b>69.870</b>
	Silica	60676-86-0	86.00	Encapsulation	0.409223	
	Epoxy Resin	Trade Secret	7.50	Encapsulation	0.035688	
	Carbon Black	1333-86-4	0.50	Encapsulation	0.002379	
	Epoxy Cresol Novolac	29690-82-2	2.00	Encapsulation	0.009517	
	Phenolic Resin	Trade Secret	4.00	Encapsulation	0.019034	
<b>Lead Frame</b>					<b>0.186398</b>	<b>27.370</b>
	Copper	7440-50-8	97.50	Base Metal	0.181738	
	Iron	7439-89-6	2.35	Base Metal	0.004380	
	Phosphorus	7723-14-0	0.03	Base Metal	0.000056	
	Zinc	7440-66-6	0.12	Base Metal	0.000224	
<b>Lead Frame Plating</b>					<b>0.000830</b>	<b>0.122</b>
	Silver	7440-22-4	100.00	Base Metal	0.000830	
<b>Gold Wire</b>					<b>0.000560</b>	<b>0.082</b>
	Gold	7440-57-5	100.00	Wire	0.000560	
<b>External Plating</b>					<b>0.010100</b>	<b>1.483</b>
	Tin	7440-31-5	85.00	Base Metal	0.008585	
	Lead	7439-92-1	15.00	Base Metal	0.001515	

## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
10/05/06	1.0	Initial Release
01/16/12	1.1	CAS# Update
11/22/12	1.2	Updated component weights

## Notice of Disclaimer

Xilinx regards this materials data to be correct but makes no guarantee as to its accuracy or completeness, including, but not limited to, with respect to its compliance with applicable environmental laws and regulations. Xilinx subcontracts the production, test and assembly of hardware devices to independent third-party vendors and materials suppliers (“Contractors”). All data provided hereunder is based on information received from Contractors. Xilinx has not independently verified the accuracy or completeness of this information which is provided solely for your reference in connection with the use of Xilinx products.